Moisture Sensitivity Level Rating Change for HMC7357

Qualification Results Summary

MSL-3 Rating Change for HMC7357 Device

QUALIFICATION RESULTS			
TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
Temperature Cycle (TC)*	JEDEC JESD22-A104	366	Pass
Solder Heat Resistance (SHR)*	JEDEC/IPC J-STD-020	30	Pass

* These samples were subjected to preconditioning (per j-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: 1. Bake – 24 hours at 125°C; 2. Soak – unbiased soak for 192 hours at 30°C, 60% RH; 3. Reflow – three passes through a reflow oven with a peak temperature of 260°C.